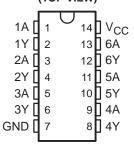
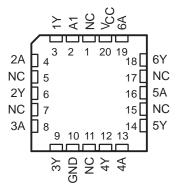
- 2-V to 6-V V_{CC} Operation
- Inputs Accept Voltages to 6 V
- Max t_{pd} of 9.5 ns at 5 V

SN54AC14 ... J OR W PACKAGE SN74AC14 ... D, DB, N, NS, OR PW PACKAGE (TOP VIEW)



SN54AC14 ... FK PACKAGE (TOP VIEW)



NC - No internal connection

description/ordering information

These Schmitt-trigger devices contain six independent inverters. They perform the Boolean function $Y = \overline{A}$. Because of the Schmitt action, they have different input threshold levels for positive-going (V_{T+}) and for negative-going (V_T_) signals.

These circuits are temperature compensated and can be triggered from the slowest of input ramps and still give clean, jitter-free output signals. They also have a greater noise margin than conventional inverters.

ORDERING INFORMATION

TA	PACKAGI	ʆ	ORDERABLE PART NUMBER	TOP-SIDE MARKING		
	PDIP – N	Tube	SN74AC14N	SN74AC14N		
	0010 P	Tube	SN74AC14D	1011		
	SOIC - D	Tape and reel	SN74AC14DR	AC14		
-40°C to 85°C	SOP - NS	Tape and reel	SN74AC14NSR	AC14		
	SSOP – DB	Tape and reel	SN74AC14DBR	AC14		
	TOCOD DW	Tube	SN74AC14PW	1011		
	TSSOP – PW	Tape and reel	SN74AC14PWR	AC14		
	CDIP – J	Tube	SNJ54AC14J	SNJ54AC14J		
-55°C to 125°C	CFP – W	Tube	SNJ54AC14W	SNJ54AC14W		
	LCCC - FK	Tube	SNJ54AC14FK	SNJ54AC14FK		

[†] Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.



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FUNCTION TABLE (each inverter)

INPUT A	OUTPUT Y
Н	L
L	Н

logic diagram, each inverter (positive logic)



absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V _{CC}		–0.5 V to 7 V
Input voltage range, V _I (see Note 1)		
Output voltage range, VO (see Note 1)		$-0.5 \text{ V to V}_{CC} + 0.5 \text{ V}$
Input clamp current, I_{IK} ($V_I < 0$ or $V_I > V_{CC}$)		±20 mA
Output clamp current, IOK (VO < 0 or VO > VCO	C)	±20 mA
Continuous output current, I_O ($V_O = 0$ to V_{CC})		±50 mA
Continuous current through V _{CC} or GND		±200 mA
Package thermal impedance, θ _{JA} (see Note 2)	: D package	86°C/W
	DB package	96°C/W
	N package	80°C/W
	NS package	76°C/W
	PW package	113°C/W
Storage temperature range, T _{stq}		–65°C to 150°C

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output voltage ratings may be exceeded if the input and output current ratings are observed.

recommended operating conditions (see Note 3)

			SN54	AC14	SN74	AC14	
			MIN	MAX	MIN	MAX	UNIT
VCC	Supply voltage		2	6	2	6	V
VI	Input voltage		0	VCC	0	VCC	V
VO	Output voltage		0	VCC	0	VCC	V
	High-level output current	VCC = 3 V		-12		-12	
lOH		V _{CC} = 4.5 V		-24		-24	mA
		V _{CC} = 5.5 V		-24		-24	
		VCC = 3 V		12		12	
lOL	Low-level output current	V _{CC} = 4.5 V		24		24	mA
		V _{CC} = 5.5 V		24		24	
T_A	Operating free-air temperature		-55	125	-40	85	°C

NOTE 3: All unused inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, Implications of Slow or Floating CMOS Inputs, literature number SCBA004.



^{2.} The package thermal impedance is calculated in accordance with JESD 51-7.

SCAS522F - AUGUST 1995 - REVISED OCTOBER 2003

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

			T	A = 25°C	;	SN54	AC14	SN74/	AC14		
PARAMETER	TEST CONDITIONS	vcc	MIN	TYP	MAX	MIN	MAX	MIN	MAX	UNIT	
V _{T+}		3 V	0.8	1.8	2.2	0.8	2.2	0.8	2.2		
Positive-going		4.5 V	1.5	2.6	3.2	1.5	3.2	1.5	3.2	V	
threshold		5.5 V	1.6	3.2	3.9	1.6	3.9	1.6	3.9		
V _T _		3 V	0.5	0.8	1	0.5	1	0.5	1		
Negative-going		4.5 V	0.9	1.4	1.8	0.9	1.8	0.9	1.8	V	
threshold		5.5 V	1.1	1.8	2.3	1.1	2.3	1.1	2.3		
ΔVT		3 V	0.3	1	1.2	0.3	1.2	0.3	1.2		
Hysteresis		4.5 V	0.4	1.2	1.4	0.4	1.4	0.4	1.4	V	
$(V_{T+} - V_{T-})$		5.5 V	0.5	1.4	1.6	0.5	1.6	0.5	1.6		
		3 V	2.9			2.9		2.9			
	I _{OH} = -50 μA	4.5 V	4.4			4.4		4.4		V	
		5.5 V	5.4			5.4		5.4			
	I _{OH} = -12 mA	3 V	2.56			2.4		2.48			
Voн	Jan. 24 mA	4.5 V	3.86			3.7		3.8			
	$I_{OH} = -24 \text{ mA}$	5.5 V	4.86			4.7		4.8			
	I _{OH} = -50 mA [†]	5.5 V				3.85					
	$I_{OH} = -75 \text{ mA}^{\dagger}$	5.5 V						3.85			
		3 V		0.002	0.1		0.1		0.1		
	I _{OL} = 50 μA	4.5 V		0.001	0.1		0.1		0.1		
		5.5 V		0.001	0.1		0.1		0.1		
.,	I _{OL} = 12 mA	3 V			0.36		0.5		0.44	V	
VOL	1 24 4	4.5 V			0.36		0.5		0.44	V	
	$I_{OL} = 24 \text{ mA}$	5.5 V			0.36		0.5		0.44		
	$I_{OL} = 50 \text{ mA}^{\dagger}$	5.5 V					1.65				
	I _{OL} = 75 mA [†]	5.5 V							1.65		
ΙĮ	V _I = V _{CC} or GND	5.5 V			±0.1		±1		±1	μΑ	
Icc	$V_I = V_{CC}$ or GND, $I_O = 0$	5.5 V			2		40		20	μΑ	
Ci	VI = V _{CC} or GND	5 V		4.5						pF	

[†] Not more than one output should be tested at a time, and the duration of the test should not exceed 10 ms.

switching characteristics over recommended operating free-air temperature range, V_{CC} = 3.3 V $\,\pm\,$ 0.3 V (unless otherwise noted) (see Figure 1)

DADAMETED	FROM	то	T,	4 = 25°C	;	SN54/	AC14	SN74/	AC14	
PARAMETER	(INPUT)	(OUTPUT)	MIN	TYP	MAX	MIN	MAX	MIN	MAX	UNIT
t _{PLH}	Δ.	V	1.5	6	13.5	1	16	1.5	15	
^t PHL	А	Y	1.5	6	11.5	1	14	1.5	13	ns

SCAS522F - AUGUST 1995 - REVISED OCTOBER 2003

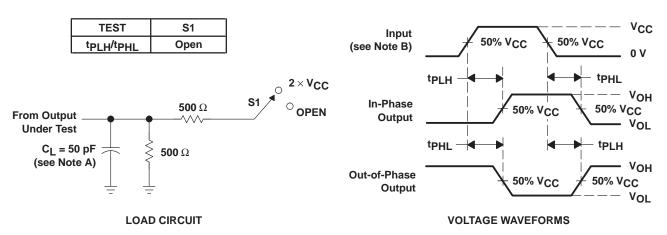
switching characteristics over recommended operating free-air temperature range, V_{CC} = 5 V \pm 0.5 V (unless otherwise noted) (see Figure 1)

	FROM		T _A = 25°C			SN54AC14		SN74AC14		
PARAMETER	(INPUT)	(OUTPUT)	MIN	TYP	MAX	MIN	MAX	MIN	MAX	UNIT
tPLH	٨	V	1.5 5 10	10	1.5	12	1.5	11		
^t PHL	А	Y	1.5	5	8.5	1.5	10	1.5	9.5	ns

operating characteristics, $V_{CC} = 5 \text{ V}$, $T_A = 25^{\circ}\text{C}$

	PARAMETER	TEST CONDITIONS	TYP	UNIT
C _{pd}	Power dissipation capacitance	$C_L = 50 \text{ pF}, \qquad f = 1 \text{ MHz}$	25	pF

PARAMETER MEASUREMENT INFORMATION



NOTES: A. C_I includes probe and jig capacitance.

- B. All input pulses are supplied by generators having the following characteristics: PRR \leq 1 MHz, $Z_O = 50 \Omega$, $t_f \leq 2.5$ ns. $t_f \leq 2.5$ ns.
- C. The outputs are measured one at a time with one input transition per measurement.

Figure 1. Load Circuit and Voltage Waveforms

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microcontroller.ti.com	Security	www.ti.com/security
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PACKAGING INFORMATION

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	e Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp ⁽³⁾
5962-87624012A	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type
5962-8762401CA	ACTIVE	CDIP	J	14	1	TBD	A42 SNPB	N / A for Pkg Type
5962-8762401DA	ACTIVE	CFP	W	14	1	TBD	A42	N / A for Pkg Type
5962-8762401VCA	ACTIVE	CDIP	J	14	1	TBD	A42 SNPB	N / A for Pkg Type
5962-8762401VDA	ACTIVE	CFP	W	14	1	TBD	A42	N / A for Pkg Type
SN74AC14D	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AC14DBLE	OBSOLETE	SSOP	DB	14		TBD	Call TI	Call TI
SN74AC14DBR	ACTIVE	SSOP	DB	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AC14DBRE4	ACTIVE	SSOP	DB	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AC14DBRG4	ACTIVE	SSOP	DB	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AC14DE4	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AC14DG4	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AC14DR	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AC14DRE4	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AC14DRG4	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AC14N	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN74AC14NE4	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN74AC14NSR	ACTIVE	SO	NS	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AC14NSRE4	ACTIVE	SO	NS	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AC14NSRG4	ACTIVE	SO	NS	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AC14PW	ACTIVE	TSSOP	PW	14	90	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AC14PWE4	ACTIVE	TSSOP	PW	14	90	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AC14PWG4	ACTIVE	TSSOP	PW	14	90	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AC14PWLE	OBSOLETE	TSSOP	PW	14		TBD	Call TI	Call TI
SN74AC14PWR	ACTIVE	TSSOP	PW	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AC14PWRE4	ACTIVE	TSSOP	PW	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AC14PWRG4	ACTIVE	TSSOP	PW	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SNJ54AC14FK	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type



PACKAGE OPTION ADDENDUM

9-Oct-2007

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins I	Package Qty	Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp ⁽³⁾
SNJ54AC14J	ACTIVE	CDIP	J	14	1	TBD	A42 SNPB	N / A for Pkg Type
SNJ54AC14W	ACTIVE	CFP	W	14	1	TBD	A42	N / A for Pkg Type

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in

a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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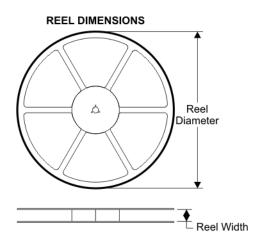
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4-Oct-2007

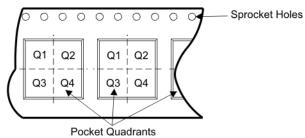
TAPE AND REEL BOX INFORMATION



TAPE DIMENSIONS KO P1 BO W Cavity A0

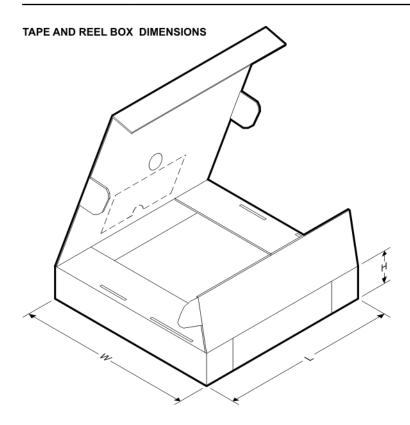
A	۸0	Dimension designed to accommodate the component width
E	30	Dimension designed to accommodate the component length
K	(0	Dimension designed to accommodate the component thickness
	Ν	Overall width of the carrier tape
ΓĒ	21	Pitch between successive cavity centers

QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



Device	Package	Pins		Reel Diameter (mm)	Reel Width (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74AC14DBR	DB	14	SITE 41	330	16	8.2	6.6	2.5	12	16	Q1
SN74AC14DR	D	14	SITE 27	330	16	6.5	9.0	2.1	8	16	Q1
SN74AC14DR	D	14	SITE 41	330	16	6.5	9.0	2.1	8	16	Q1
SN74AC14NSR	NS	14	SITE 41	330	16	8.2	10.5	2.5	12	16	Q1
SN74AC14PWR	PW	14	SITE 41	330	12	7.0	5.6	1.6	8	12	Q1





Device	Package	Pins	Site	Length (mm)	Width (mm)	Height (mm)
SN74AC14DBR	DB	14	SITE 41	346.0	346.0	33.0
SN74AC14DR	D	14	SITE 27	342.9	336.6	28.58
SN74AC14DR	D	14	SITE 41	346.0	346.0	33.0
SN74AC14NSR	NS	14	SITE 41	346.0	346.0	33.0
SN74AC14PWR	PW	14	SITE 41	346.0	346.0	29.0

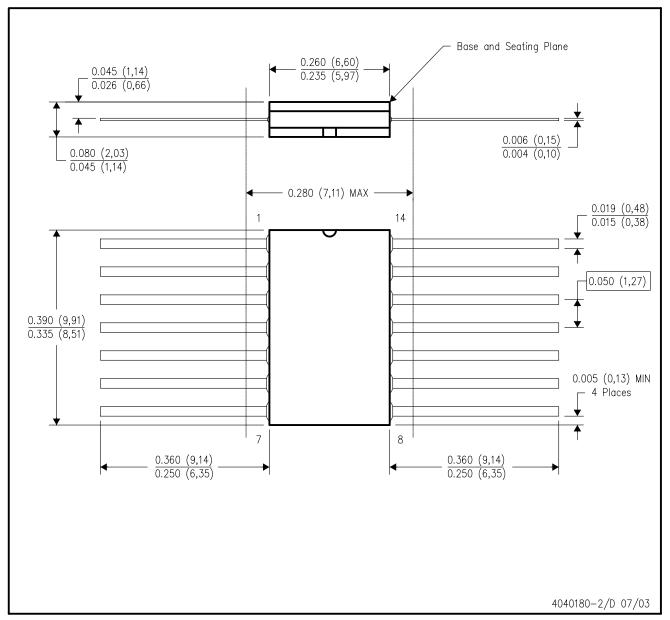
14 LEADS SHOWN



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. This package is hermetically sealed with a ceramic lid using glass frit.
- D. Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
- E. Falls within MIL STD 1835 GDIP1-T14, GDIP1-T16, GDIP1-T18 and GDIP1-T20.

W (R-GDFP-F14)

CERAMIC DUAL FLATPACK



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. This package can be hermetically sealed with a ceramic lid using glass frit.
- D. Index point is provided on cap for terminal identification only.
- E. Falls within MIL STD 1835 GDFP1-F14 and JEDEC MO-092AB



FK (S-CQCC-N**)

28 TERMINAL SHOWN

LEADLESS CERAMIC CHIP CARRIER



NOTES: A. All linear dimensions are in inches (millimeters).

- B. This drawing is subject to change without notice.
- C. This package can be hermetically sealed with a metal lid.
- D. The terminals are gold plated.
- E. Falls within JEDEC MS-004



N (R-PDIP-T**)

PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN

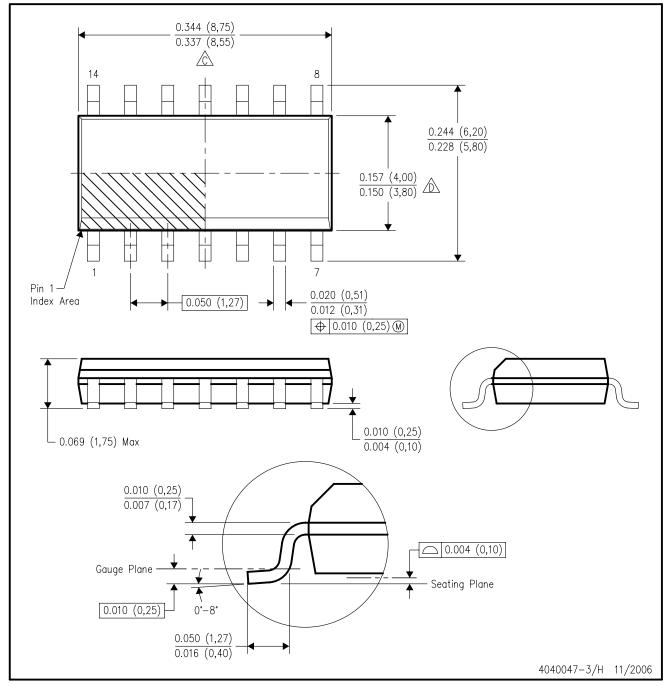


- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
- The 20 pin end lead shoulder width is a vendor option, either half or full width.



D (R-PDSO-G14)

PLASTIC SMALL-OUTLINE PACKAGE



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed .006 (0,15) per end.
- Body width does not include interlead flash. Interlead flash shall not exceed .017 (0,43) per side.
- E. Reference JEDEC MS-012 variation AB.



MECHANICAL DATA

NS (R-PDSO-G**)

14-PINS SHOWN

PLASTIC SMALL-OUTLINE PACKAGE



- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.



DB (R-PDSO-G**)

PLASTIC SMALL-OUTLINE

28 PINS SHOWN



NOTES: A. All linear dimensions are in millimeters.

B. This drawing is subject to change without notice.

C. Body dimensions do not include mold flash or protrusion not to exceed 0,15.

D. Falls within JEDEC MO-150

PW (R-PDSO-G**)

14 PINS SHOWN

PLASTIC SMALL-OUTLINE PACKAGE



NOTES: A. All linear dimensions are in millimeters.

B. This drawing is subject to change without notice.

C. Body dimensions do not include mold flash or protrusion not to exceed 0,15.

D. Falls within JEDEC MO-153



Компания «ЭлектроПласт» предлагает заключение долгосрочных отношений при поставках импортных электронных компонентов на взаимовыгодных условиях!

Наши преимущества:

- Оперативные поставки широкого спектра электронных компонентов отечественного и импортного производства напрямую от производителей и с крупнейших мировых складов:
- Поставка более 17-ти миллионов наименований электронных компонентов;
- Поставка сложных, дефицитных, либо снятых с производства позиций;
- Оперативные сроки поставки под заказ (от 5 рабочих дней);
- Экспресс доставка в любую точку России;
- Техническая поддержка проекта, помощь в подборе аналогов, поставка прототипов;
- Система менеджмента качества сертифицирована по Международному стандарту ISO 9001:
- Лицензия ФСБ на осуществление работ с использованием сведений, составляющих государственную тайну;
- Поставка специализированных компонентов (Xilinx, Altera, Analog Devices, Intersil, Interpoint, Microsemi, Aeroflex, Peregrine, Syfer, Eurofarad, Texas Instrument, Miteq, Cobham, E2V, MA-COM, Hittite, Mini-Circuits, General Dynamics и др.);

Помимо этого, одним из направлений компании «ЭлектроПласт» является направление «Источники питания». Мы предлагаем Вам помощь Конструкторского отдела:

- Подбор оптимального решения, техническое обоснование при выборе компонента;
- Подбор аналогов;
- Консультации по применению компонента;
- Поставка образцов и прототипов;
- Техническая поддержка проекта;
- Защита от снятия компонента с производства.



Как с нами связаться

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